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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

SERIAL NO: 09 770,289

GAU: 1712

FILED: January 29, 2001

EXAMINER: FEELY, M.J.

FOR PROCESS FOR PRODUCING SILICA-BASED FILM, SILICA-BASED FILM, INSULATING FILM, AND SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment form is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

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Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 202450US0		SERIAL NO. 09/770,289			
<div style="border: 1px solid black; border-radius: 50%; padding: 10px; display: inline-block;"> O I P E J C I S A OCT 09 2003 PATENT & TRADEMARK OFFICE </div>				APPLICANT Atsushi SHIOTA, et al.				GROUP 1712	
LIST OF REFERENCES CITED BY APPLICANT				FILING DATE January 29, 2001					
U.S. PATENT DOCUMENTS									
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE		
	AA	6,207,555 B1	03/27/2001	Matthew ROSS					
	AB	6,548,899 B2	04/15/2003	Matthew ROSS					
	AC	6,271,146 B1	08/07/2001	Matthew ROSS					
	AD	6,582,777 B1	06/24/2003	Matthew ROSS, et al.					
	AE	US 2003/0008481 A1	01/09/2003	Matthew ROSS, et al.					
	AF	6,489,225 B1	12/03/2002	Matthew ROSS, et al.					
	AG	US 2003/0102084 A1	06/05/2003	William LIVESAY, et al.					
	AH	6,426,127 B1	07/30/2002	Matthew ROSS, et al.					
	AI	6,358,670 B1	03/19/2002	Selmer WONG, et al.					
	AJ	6,319,655 B1	11/20/2001	Selmer WONG, et al.					
	AK								
	AL								
	AM								
	AN								
FOREIGN PATENT DOCUMENTS									
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO				
	AO	JP2001015500	01/19/2001	JAPAN (English-language Abstract only)					
	AP								
	AQ								
	AR								
	AS								
	AT								
	AU								
	AV								
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)									
	AW	J.J. YANG, et al., "Electron Beam Curing of Siloxane SOG for Non-etch Back Process". Advanced Metallization & Interconnect Systems for ULSI Applications in 1996: Materials Research Society Conference Proceedings, ed. Robert Havemann, et al., May 1997, pp. 505-509.							
	AX	J.J. YANG, et al., "Integration of Spin-on Low-k Dielectrics Using E-Beam Curing for ULSI Multilevel Interconnects". Advanced Metallization and Interconnect Systems for ULSI Applications in 1997: Materials Research Society Conference Proceedings, ed. R. Cheung, et al., March 1999, pp. 359-365.							
	AY	Applied Materials' assertion that Matthew Ross is a co-inventor of the 09/770,289 application. See discussion in Amendment filed herewith.							
	AZ								
					<input type="checkbox"/> Additional References sheet(s) attached				